

#### Description

The 25N50 uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gat e charge. It can be used in a wide variety of applications.

#### **General Features**

V<sub>DS</sub> =500V,I<sub>D</sub> =25A

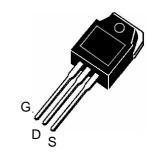
 $R_{DS(ON)} < 240 m_{\Omega} @ V_{GS} = 10V$ 

#### Application

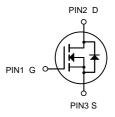
High efficiency switch mode power supplies

Power factor correction

Electronic lamp ballast







N-Channel MOSFET

#### Package Marking and Ordering Information

Product ID	Pack	Marking	Units Tube
		5	
25N50	TO-3P	HXY 25N50 YYYY	50

### Absolute Maximum Ratings@Tj=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	500	V
VGS	Gate-Source Voltage	<u>+</u> 20	V
I₀@Tc=25°C	Drain Current	25	А
IDM	Pulsed Drain Current <sup>1</sup>	100	А
P₀@Tc=25℃	Total Power Dissipation	300	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C



Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	<b>i</b> i		•			•
Drain-Source Breakdown Voltage <sup>(Note 1)</sup>	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	500	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =500V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics	· · ·		•			•
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	2.0	-	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =14A	-	200	240	mΩ
Forward Transconductance	<b>G</b> FS	V <sub>DS</sub> =40V,I <sub>D</sub> =10A	-	25	-	S
Dynamic Characteristics	· · ·		•	•		•
Input Capacitance	Clss	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V, F=1.0MHz	-	3500	-	PF
Output Capacitance	Coss		-	220	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	12	-	PF
Switching Characteristics			·			
Turn-on Delay Time	t <sub>d(on)</sub>	$V_{DD}$ =400V,I <sub>D</sub> =25A R <sub>G</sub> =10 $\Omega^{(Note 2)}$	-	40	-	nS
Turn-on Rise Time	tr		-	68	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	88	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	44	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =400V,I <sub>D</sub> =25A, V <sub>GS</sub> =10V <sup>(Note 2)</sup>	-	65	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	12	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	v <sub>GS</sub> -10v	-	20	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =14A	-		1.4	V
Diode Forward Current (Note 2)	Is		-	-	25	А

#### Electrical Characteristics (Tc=25°C unless otherwise noted)

#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

**2.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.



## **Typical Electrical**

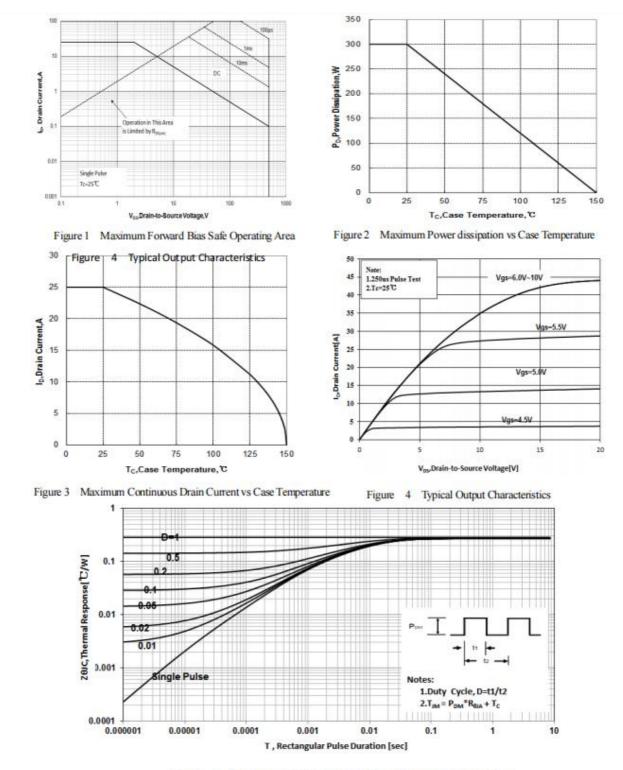
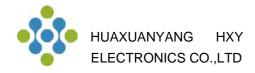


Figure 5 Maximum Effective Thermal Impedance, Junction to Case

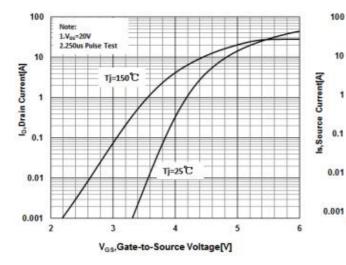


Tj-25°C

1

1.2

8.0







Vsp. Source-to-Drain Voltage[V]

0.6

100

10

1

0.1

0.01

0

Tj=150°C

0.4

0.2

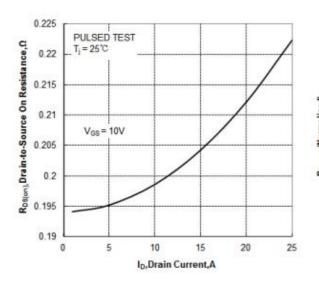


Figure 8 Typical Drain to Source ON Resistance vs Drain Current

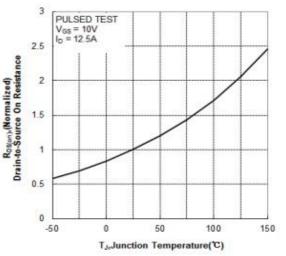
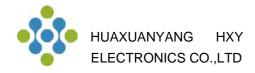
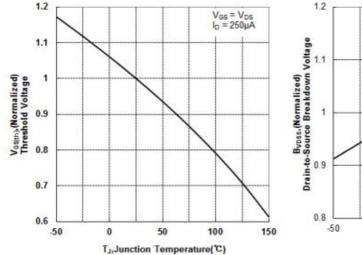


Figure 9 Typical Drian to Source on Resistance vs Junction Temperature





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Figure 10 Typical Theshold Voltage vs Junction Temperature

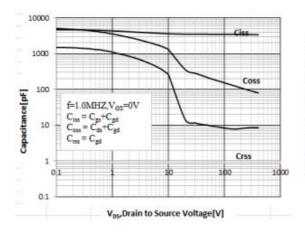


Figure 12 Typical Capacitance vs Drain to Source Voltage

Figure 11 Typical Breakdown Voltage vs Junction Temperature

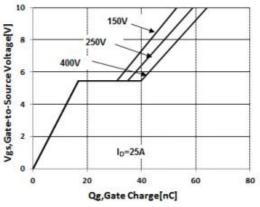
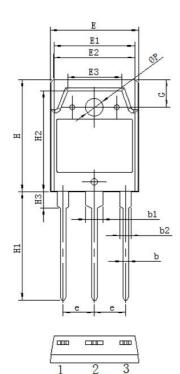


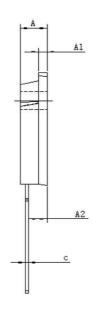
Figure 13 Typical Gate Charge vs Gate to Source Voltage



# Package Information

TO-3P





Symbol	单位 mm			
	Min	Nom	Max	
A	4.60	4.80	5. 00	
A1	1.3	1.5	1.7	
A2	1.20	1.40	1. 60	
b	0.80	1.0	1.20	
b1	2.90	3.10	3. 30	
b2	1.90	2.10	2. 30	
с	0.50	0.60	0.70	
e	5.25	5.45	5.65	
E	15.2	15.6	16.0	
E1	13.2	13.4	13.6	
E2	13.1	13.3	13.5	
E3	9.1	<mark>9.</mark> 3	9.5	
Н	19.8	20.0	20. 2	
H1	20.1	20. 3	20. 5	
H2	18.5	18.7	18.9	
H3	3.2	3.5	3.8	
G	4.8	5.0	5.2	
ΦΡ	3.00	3.20	3.40	



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